

2019 Editorial Calendar

| <i>(Editorial close date: 6/15)</i> | July • August | Industry Events * indicates show distribution |
|--|---------------|--|
| Advances in inspection | | <ul style="list-style-type: none"> • ICEPT 2019 Shanghai, China (Aug 11-15) • SEMICON Taiwan * Taipei, Taiwan (Sept 18-20) • European MEMS & Sensors Summit Grenoble, France (Sept 19-21) • European Imaging & Sensors Summit Grenoble, France (Sept 19-21) • SMTA International Rosemont, IL (September 22-26) |
| Inkjet printing for packaging applications | | |
| Overview and outlook of heterogeneous integrations | | |
| Reliability physics analysis | | |
| Die to wafer hybrid bonding | | |
| MEMS & Sensors | | |
| Ultra-thin packaged ICs | | |
| Glass carriers for temporary bonding | | |
| Large-area fan-out processing | | |

Ad Space Close Jun 28 - Ad Materials Close Jul 8

| <i>(Editorial close date: (8/2)</i> | September • October | Industry Events * indicates show distribution |
|---|---------------------|--|
| Material challenges and solutions for advanced SiP | | <ul style="list-style-type: none"> • IWLPC-International Wafer-Level Packaging Conference & Exhibition * San Jose, CA (Oct 22-24) • IMPACT Taipei, Taiwan (October 24-26) • TestConX China 2019 Suzhou, China (Oct 23) • Shenzhen, China (Oct 25) • International Test Conference (ITC) Phoenix, AZ (Oct 28- Nov 2) • SEMI International Technology Partners Conference (ITPC) Maui, Hawaii (Nov 4-7) • SEMICON Europa / Productronica Munich, Germany (Nov 12-16) • EPTC 2019 Singapore (Dec 3-6) |
| Embedded RDL | | |
| High density flip-chip and advanced CSP | | |
| High-resolution 3D X-ray metrology | | |
| Advanced substrates and embedded packaging | | |
| High density advanced packaging (HDAP) design | | |
| Technology trends – OSATs | | |
| Temporary bonding for high temperature processing of thin glass | | |
| Smart devices and applications | | |

International Directory of Defect Inspection Systems

Ad Space Close Sep 6 - Ad Materials Close Sep 13

| <i>(Editorial close date: 10/4)</i> | November • December | Industry Events * indicates show distribution |
|--|---------------------|--|
| Collective bonding for heterogeneous integration | | <ul style="list-style-type: none"> • SEMICON Japan Tokyo, Japan (Dec 11-13) • SEMI European 3D Summit * Dresden, Germany (TBD) • APEX Expo San Diego, CA USA (Jan 26-31, 2020) • SEMI European 3D & Systems Summit Dresden, Germany (Jan 28-30, 2020) • SEMICON Korea 2020 * Coex, Seoul, Korea (Feb 5-7, 2020) |
| Cooling solutions for hi-density chips | | |
| Advanced eWLB for mmWave applications | | |
| High temperature survivability & the processes it allows | | |
| TSV and RDL technologies, the road ahead | | |
| Multi-die/ substrate heterogeneous packages | | |
| Advanced IC and MEMS packaging technologies | | |
| 3D ICs | | |
| 5G challenges | | |

Ad Space Close Nov 3 - Materials Close Nov 10

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